

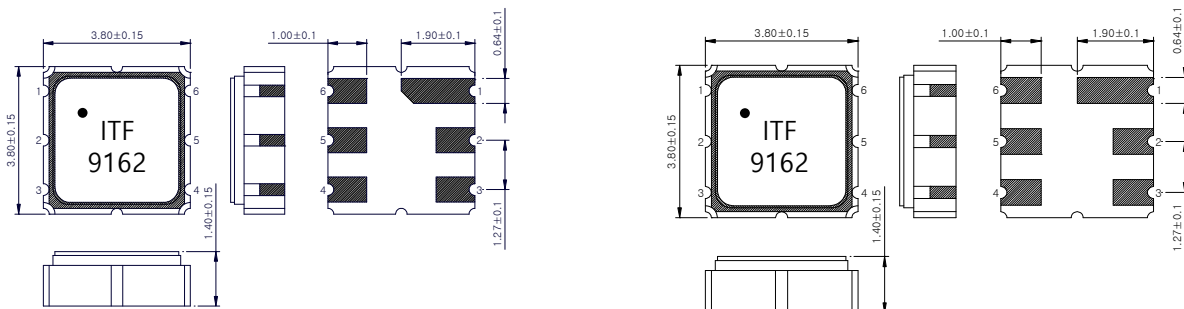
## 1. Features

- RF SAW Band Pass filter
- Usable Passband **0.22 MHz**
- Ceramic Surface Mounted Device Package ( 3.8 mm × 3.8 mm )
- RoHS Compliant

**RoHS Compliant**

Tested by SGS Testing Korea

## 2. Package Dimension



Dimensions shown are nominal in millimeters

Body : Al<sub>2</sub>O<sub>3</sub> Ceramic

Lid : Kovar, Ni Plated

Terminations : Au plating 0.3 ~ 1.0 um, Over a 1.27 ~ 8.89 um

Ni Plating

Pin Configuration			
Input	2	Output	5
Ground	Others		

## 3. Maximum Rating

Parameter	Unit	Minimum	Typical	Maximum
Operating Temperature Range	°C	-30	+25	+85
Storage Temperature Range		-40	+25	+85
Maximum DC Voltage <sup>1)</sup>	V			
Maximum Input Power	dBm			10

1) Maximum DC Voltage : TBD

Electrostatics Sensitive Device

#### 4. Electrical Specifications

##### Room Temperature : +25 °C

		Minimum	Typical	Maximum
Center Frequency ( Fc )	MHz	-	916.3	-
Insertion Loss (Fc +/- 110 kHz)	dB	-	6.5	8.0
Amplitude Ripple (Fc +/- 110 kHz)	dB	-	0.5	1.2
3dB Bandwidth	MHz	0.50	0.70	-
Relative Attenuation				
911.0 MHz ~ 913.5 MHz	dBc	35	40	-
913.5 MHz ~ 915.0 MHz		25	35	-
917.0 MHz ~ 918.0 MHz		20	23	-
918.0 MHz ~ 921.0 MHz		35	40	-
Input/Output Impedance	Ohm	-	50	-

##### Operating Temperature :-30 ~ + 85 °C

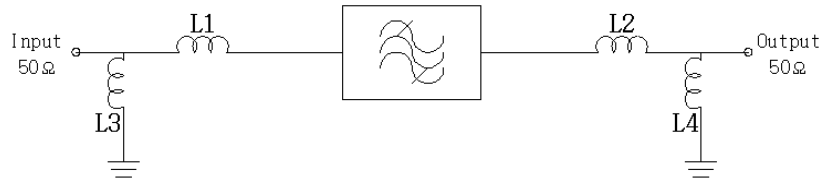
		Minimum	Typical	Maximum
Center Frequency ( Fc )	MHz	-	916.3	-
Insertion Loss (Fc +/- 110 kHz)	dB	-	6.5	9.0
Amplitude Ripple (Fc +/- 110 kHz)	dB	-	0.5	3.0
3dB Bandwidth	MHz	0.50	0.70	-
Relative Attenuation				
911.0 MHz ~ 913.5 MHz	dBc	35	40	-
913.5 MHz ~ 915.0 MHz		25	35	-
917.0 MHz ~ 918.0 MHz		20	23	-
918.0 MHz ~ 921.0 MHz		35	40	-
Input/Output Impedance	Ohm	-	50	-

#### Notes :

- 1) All specifications are based on the matching schematic shown below, measured by Agilent Network analyzer and full 2 port calibration.
- 2) Electrical margin has been built into the design to account for the variations due to temperature drift and manufacturing tolerances
- 3) All attenuation measurements are measured relative to insertion loss

## 5. Matching schematic

( Actual matching values may vary due to PCB layout and parasitics )



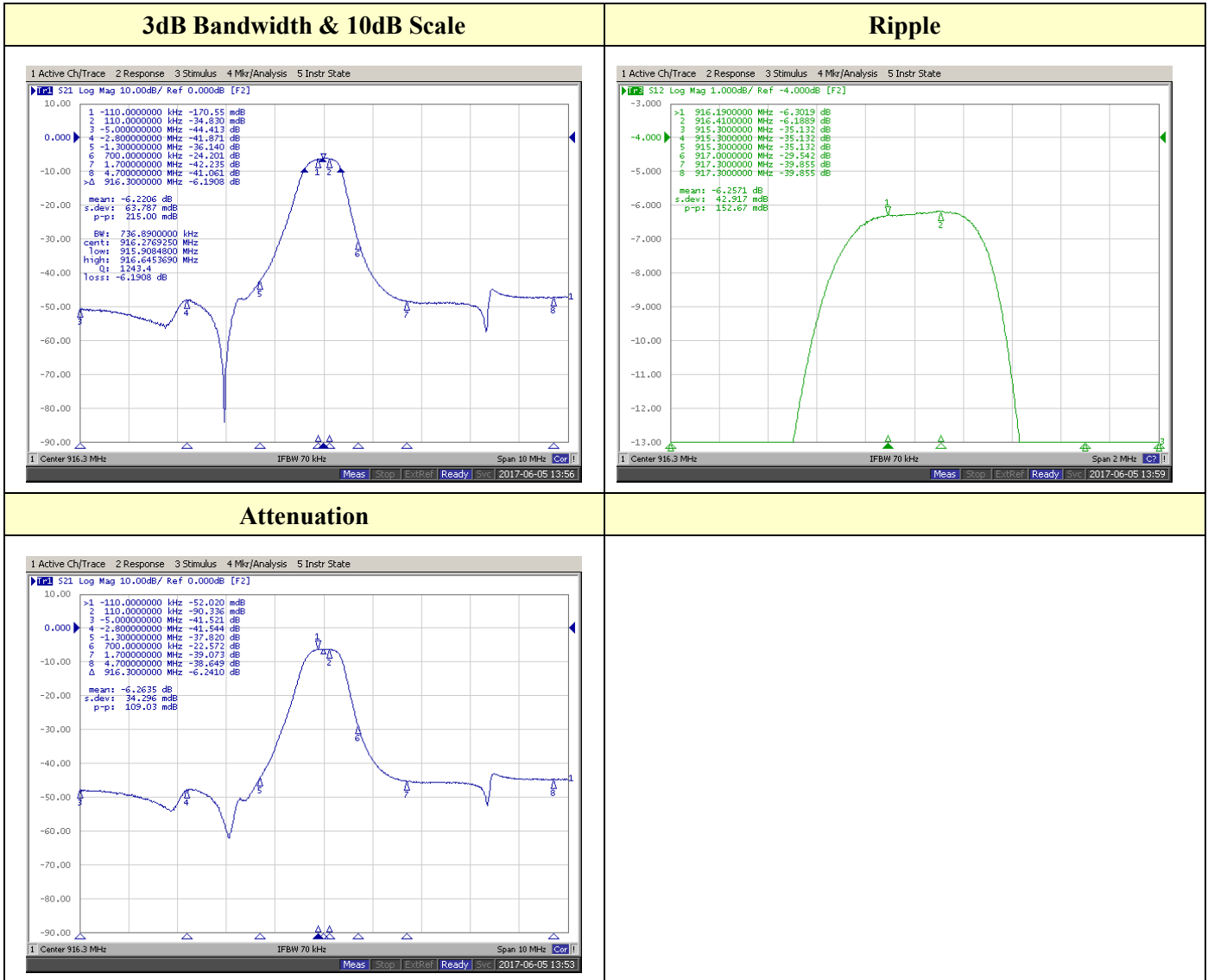
$$L1 = 12\text{nH}, L2 = 12\text{nH}, L3 = 22\text{nH}, C1 = 5.6\text{pF}$$

## 6. Marking configuration

- 1)  
ITF 2)  
9162 3)

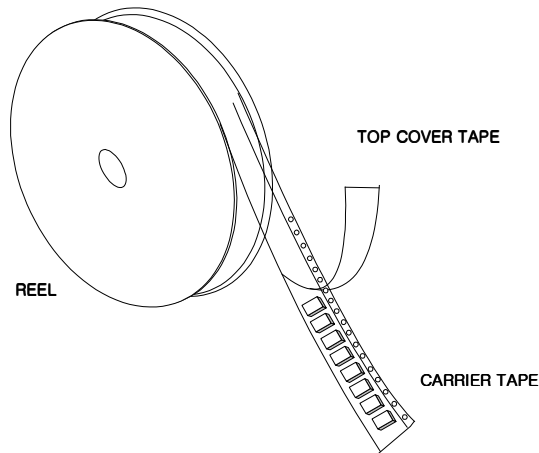
- 1) Index Pin No.1
- 2) Manufacturer name
- 3) Marking Number

**7. Typical Performance ( at +25°C )**



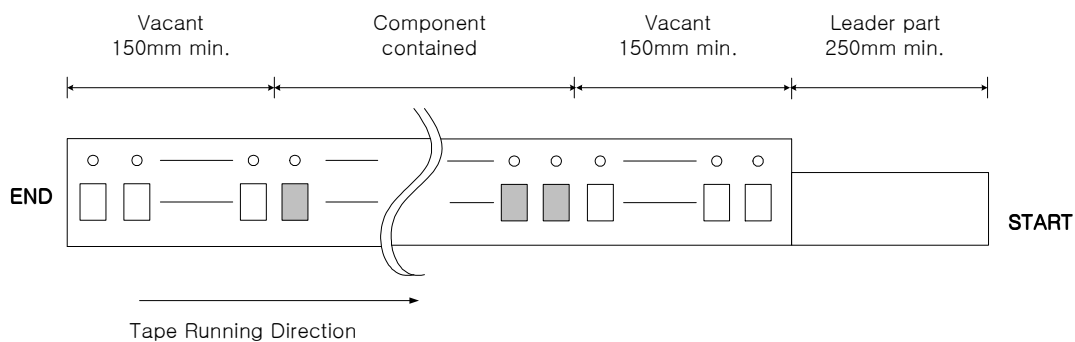
## 8. Packing Specification

1. Reeling Quantity : 1000 pcs/reel or 3000pcs/reel
2. Taping Structure : The tape shall be wound around the reel in the direction shown below.



## 9. Tape Specification

1. Leader part and vacant position specification

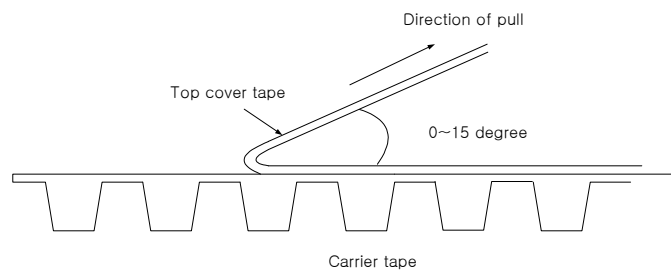


2. Tensile strength of carrier tape

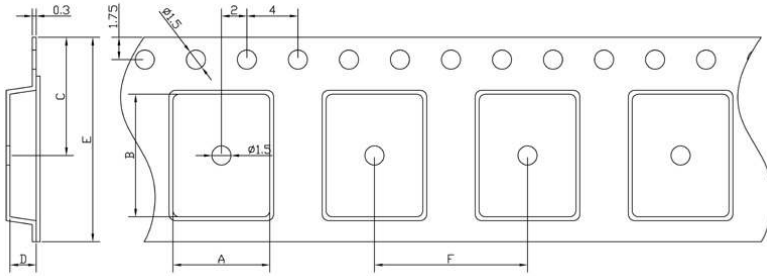
4.4N/mm width

3. Top cover tape adhesion

- 1) pull off angle : 0~15°
- 2) speed : 300mm/min
- 3) force : 20~70g

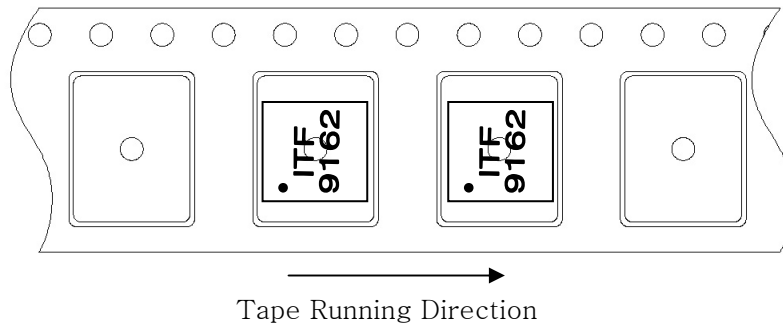


**10. Carrier Tape Dimensions [unit : mm]**



A	4.30 ± 0.1
B	4.30 ± 0.1
C	7.25 ± 0.1
D	1.70 ± 0.1
E	12.00 ± 0.1
F	8.00 ± 0.1

**11. Part Direction**



**12. Reel Dimensions [unit : mm]**

